

## APPARATUS AND METHOD FOR BGA BALL PLACEMENT

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### Abstract

10 An apparatus for placing solder balls in a ball grid array on a substrate comprises a tooling plate having a plurality of recesses formed therein, a reservoir located in juxtaposition with the tooling plate to allow for population of the recesses with balls, and means for extracting the balls from the recesses and locating the extracted balls on the substrate. A method using the apparatus of the invention for placing solder balls in a ball grid array on a substrate is also disclosed.

15 **FIG. 3**